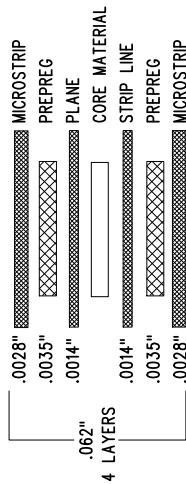
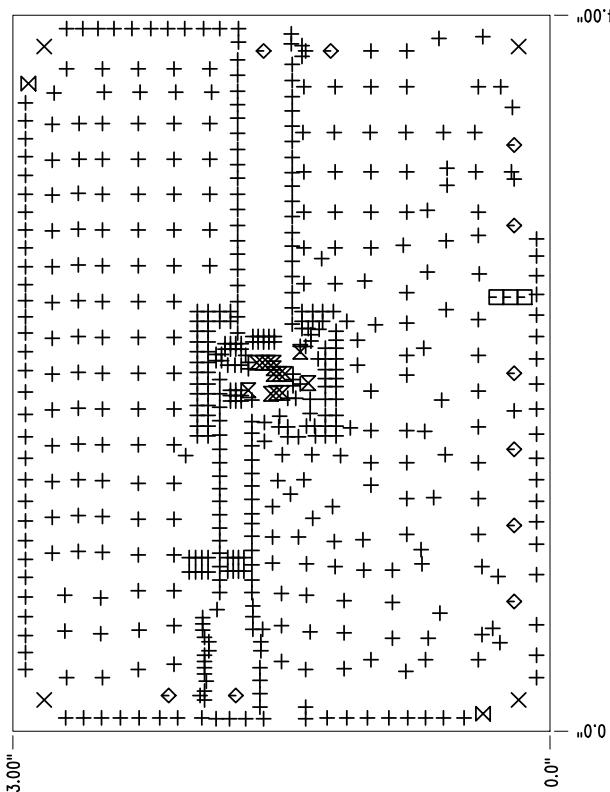


LAYER STRUCTURENOTES: UNLESS OTHERWISE SPECIFIED

1. FAB PER IPC-A-600.
2. MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR
OR EQUIVALENT ($T_g \geq 175$ DEGREES CELSIUS),
-FINISHED THICKNESS TO BE .062⁺/_{-0.005}"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS
AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-O MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
4. DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH
HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE $+/-0.003"$
IN RELATION TO CENTER
5. FINISH: -SMOEC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMMERSION BOTH SIDES.
(LEAD FREE SOLDER CAN BE USED FOR PROTOTYPE)
-FOR SILKSCREEN: BOTH SIDES USE WHITE NON-CONDUCTIVE INK.

6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
 7. PCB'S ARE TO BE RoHS COMPLIANT.
 8. SCORING FOR PANELIZED PCB:
9. DESIGN HAS SOLDER MASK DEFINED PADS ON U1
U1 SOLDER MASK SIZE IS 16 MIL AND PAD SIZE IS 20 MIL.
DO NOT CHANGE ANY SIZE ON THIS COMPONENT.



SIZE	QTY	SYM	PLATED	TOL
0.006	14	☒	YES	+/-0.003
0.01	529	+	YES	+/-0.003
0.035	3	□	YES	+/-0.003
0.095	10	◊	YES	+/-0.003
0.07	2	☒	NO	+/-0.003
0.187	4	×	NO	+/-0.003

ADDITIONAL REQUIREMENT FOR PROTOTYPE FAB ONLY:

1. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).
- ADDITIONAL REQUIREMENTS FOR PRODUCTION FAB ONLY:
 1. PROVIDE COMPLIANCE CERTIFICATES FOR RoHS, REACH AND CONFLICT-FREE MINERALS.
 2. SOLDERABILITY BOARD WITH TEST RESULTS.
 3. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).
 4. VACUUM PACKED WITH DESCICANT.
 5. FULL PANEL WITH NO REJECT

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TITLE: FABRICATION DRAWING
40VIN, 2.5A STEP DOWN
µMODULE DC/DC CONVERTER

SIZE	IC NO.	REV
N/A	LTM802HY DC2501A	2

FILENAME: DC2501A-2.PCB

SHT 1 OF 1